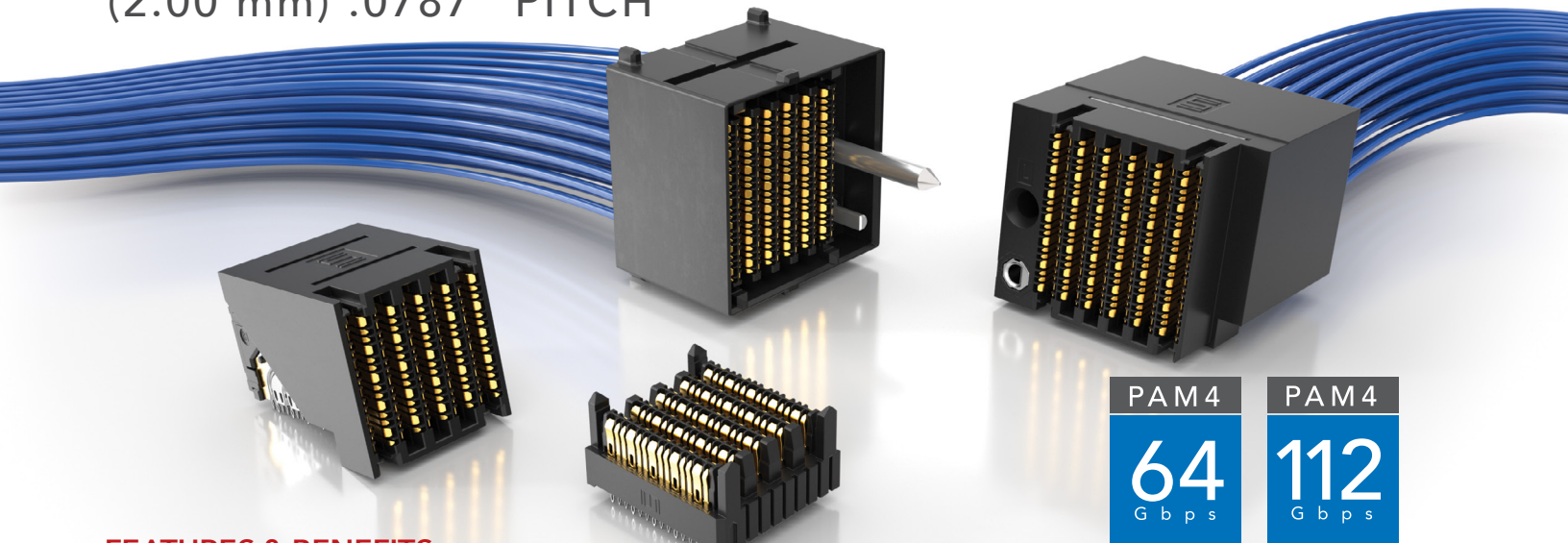


ExaMAX[®]

HIGH-SPEED BACKPLANE CONNECTOR & CABLE SYSTEMS

(2.00 mm) .0787" PITCH



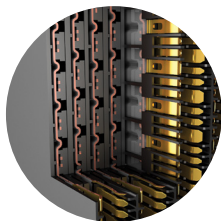
FEATURES & BENEFITS

ExaMAX[®] High-Speed Backplane System

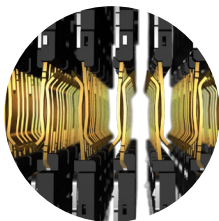
- Meets a variety of industry specifications
- Traditional, coplanar and direct mate orthogonal
- 24 - 72 pair designs (4 and 6 pairs; 6, 8, 10 and 12 columns)
- Shielded wafer design reduces crosstalk and includes one sideband signal per column
- Press-fit tails provide a reliable electrical connection
- PCIe[®] 6.0/CXL[®] 3.2 capable

ExaMAX[®] High-Speed Backplane Cable Assemblies

- 30 & 34 AWG Eye Speed[®] ultra low skew twinax cable
- 34 AWG Eye Speed Thinax[™] ultra low skew twinax cable
- Offers improved signal integrity, increased flexibility and routability
- Highly customizable with modular flexibility
- Reduce costs due to lower layer counts
- PCIe[®] 6.0/CXL[®] 3.2 capable



Staggered
Differential
Pair Design



Two Reliable Points
of Contact with
a 2.4 mm Wipe



In Development:
Open-Pin-Field,
Coplanar Configuration



In Development:
2 Pair Design for
a Lower Profile



In Development:
ExaMAX2[®] 8 Pairs
for 112 Gbps PAM4
Performance

KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
EBTM/EBTF/EBDM	Liquid Crystal Polymer	Copper Alloy	Sn or Au over 50 μ " (1.27 μ m) Ni	-55 °C to +105 °C	4 A per pin	150 VAC/212 VDC	Yes
EPTT/EPTS	High Temperature Thermoplastic	Copper Alloy	Sn or Au over 50 μ " (1.27 μ m) Ni	-55 °C to +105 °C	14.1 A per pin	150 VAC/212 VDC	Yes
EBCM/EBCF	Liquid Crystal Polymer	Copper Alloy	Au over 50 μ " (1.27 μ m) Ni	-40 °C to +105 °C	2.6 A per pin	125 VAC/177 VDC	N/A

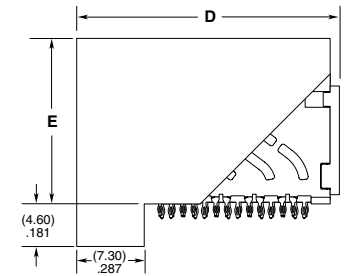
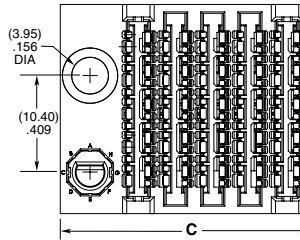
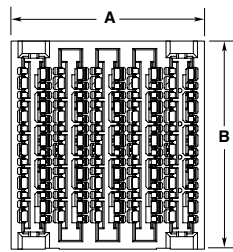
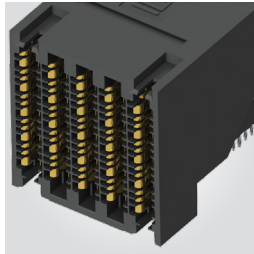
PCI-SIG[®], PCI Express[®] and the PCIe[®] design marks are registered trademarks and/or service marks of PCI-SIG.

(2.00 mm) .0787" PITCH • RIGHT-ANGLE SOCKET & DIRECT-MATE ORTHOGONAL

EBTF	NO. OF PAIRS PER COLUMN	COLUMNS	COLUMN PITCH	PLATING	RA	PIN CONFIGURATION	GUIDANCE	KEYING
	-4 = 4 Pairs -6 = 6 Pairs	-06, -08, -10, -12 (-12 column only available in -6 pairs)	-2.0 = (2.0 mm) .0787"	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tails		-1 = Standard -5 = Open Pin Field (only available in -6 pairs)	(Leave Blank for no Guidance) -L = Left Guidance -R = Right Guidance	(Only with -L or -R Guidance; Leave Blank for no Keying) -A thru -H = Position of Flat on Key (See Table)

EBTF-RA
Board Mates:
EBTM,
EBDM-RA

Cable Mates:
EBCM



KEYING (-RA)							
-L / -R	-A	-B	-C	-D	-E	-F	-G

NO. OF COLUMNS	A	C
-06	(12.90) .508	(18.85) .742
-08	(16.90) .665	(22.85) .900
-10	(20.90) .823	(26.85) 1.057
-12	(24.90) .980	(30.85) 1.215

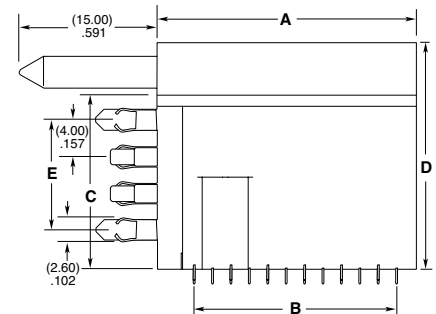
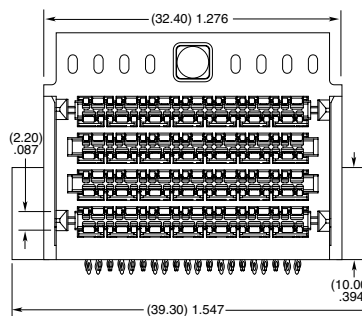
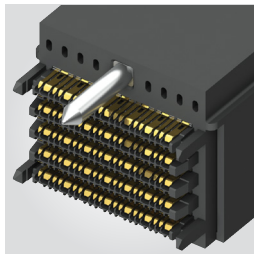
NO. OF PAIRS PER COLUMN	B	D	E
-4	(22.50) .886	(28.40) 1.118	(17.90) .705
-6	(29.70) 1.169	(35.60) 1.402	(25.10) .988

View complete specifications at: samtec.com?EBTF-RA

EBDM	PAIRS	COLUMNS	2.0	PLATING	RA	PIN CONFIGURATION	GUIDANCE	SCREW MOUNT
	-6 = 6 Pairs	-06, -08, -10, -12		-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tails		-1 = Standard	(Leave Blank for no Pin) -G = Guide Pin	(Leave Blank for no Screw Mount) -S = Screw Mount

EBDM-RA
Board Mates:
EBTF-RA

Cable Mates:
EBCF



COLUMNS	A	B	C (without -G)	D (with -G)	E
-06	(16.15) .636	(10.00) .394	(15.00) .591	(20.65) .813	(8.00) .315
-08	(20.15) .793	(14.00) .551	(19.00) .748	(24.65) .970	(12.00) .472
-10	(24.15) .951	(18.00) .709	(23.00) .906	(28.65) 1.128	(16.00) .630
-12	(28.15) 1.108	(22.00) .866	(27.00) 1.063	(32.65) 1.285	(20.00) .787

Notes:
Some lengths, styles and options are non-standard, non-returnable.

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View complete specifications at: samtec.com?EBDM-RA